IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				ler both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				Form Type ³ Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfc Information			
upplier Inform	ation								,			,		
Company name*			Company unique ID			U	Unique ID Authority				Response Date*			
nsemi											2023-06-08			
Contact Name		Title	Title - Contact			P	Phone - Contact*				Email - Contact*			
Product-Env-Stewa	ards	Prod	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
uthorized Represe	ntative*	Title	Title - Representative			P	Phone - Representative*				Email - Representative*			
Product-Env-Stewa	ards	Prod	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requeste	Requester Item Number Mfr Ite		tem Number Mfr Item Name				Effective Date	Version	ersion Manufacturing Site		W	eight*	UOM	Unit Type
		NCP45520IMNTWG- NCP45520IMNT		NCP45520IMNTW	G-L		2023-06-08 UTH		ТН	11	.76364	mg	Each	
Ianufacturing l	Process Information	n												
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MS				STD-020 MSL	Rating	Peak Proce	ss Body Te	mperature	Max Time at Peak	Temperatui	e Numb	er of Reflow Cyc	eles	
Matte Tin (Sn) - annealed		CU Alle	CU Alloy 3				260		С	30	seconds	3		
omments			·	·						<u>-</u>				·
TTENTION: MSL	3 Rated item requires Ba	ake and Dry Pac	ick (after e	lectrical test)						·				•
or more informatio	on regarding material con	nposition please	e refer to p	age 3									·	·

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.63	mg	Supplier	Silicon (Si)	7440-21-3		0.63	mg
Die Attach	0.12964	mg		Epoxy resin	proprietary data		0.0032	mg
			Supplier	Silver (Ag)	7440-22-4		0.1095	mg
			Supplier	Phenolic Resin	Proprietary Data		0.0032	mg
			Supplier	Inorganic filler	Proprietary Data		0.0032	mg
			Supplier	Dicyandiamine	461-58-5		0.0006	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.0097	mg
Die Attach Epoxy	0.03	mg		Epoxy resin	proprietary data		0.009	mg
			Supplier	Diethylene glycol monoethyl ether acetate	112-15-2		0.0105	mg
_			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.0105	mg
Lead Frame	4.29	mg	Supplier	Silver (Ag)	7440-22-4		0.0858	mg
			Supplier	Tin (Sn)	7440-31-5		0.0107	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0094	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0107	mg
			Supplier	Copper (Cu)	7440-50-8		4.1733	mg
Mold Compound-Black	6.0	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.48	mg
			Supplier	Carbon Black (C)	1333-86-4		0.03	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.12	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.19	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.18	mg
Plating	0.46	mg	Supplier	Tin (Sn)	7440-31-5		0.46	mg
Wire Bond - Au	0.224	mg	Supplier	Gold (Au)	7440-57-5		0.224	mg